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ABSTRACT

5 A probe card having multiple planes with continuous  
metal traces from a high density of small, robust probe  
contacts to peripheral vias which enable connection to a  
test head is fabricated using technology from the printed  
circuit card industry. The card includes a relatively small,  
centrally located recessed plane having a plurality of probe  
contacts precisely patterned to mate with chip contacts, an  
10 array of continuous conductive traces, the substrate is  
folded at specific crease locations, and formed upward to a  
second array of creases at which the substrate is bent to  
form a raised plane parallel to the first.

15 Integrated single unit construction, coupled with  
adaptability for rapid pattern design or changes in  
conductors readily enables a low inductance probe card, and  
its low cost, automated method of manufacture is compatible  
with tight pitch and high performance requirements of  
integrated circuits both in current production, and those in  
20 plans for the future.

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